

**FEATURES**

- n **HIGH POWER**  
P1dB=33.0dBm at 9.5GHz to 12.0GHz
- n **HIGH GAIN**  
G1dB=25.0dB at 9.5GHz to 12.0GHz
- n **BROAD BAND INTERNALLY MATCHED**
- n **HERMETICALLY SEALED PACKAGE**

**ABSOLUTE MAXIMUM RATINGS ( Ta= 25°C )**

CHARACTERISTICS	SYMBOL	UNIT	RATING
Drain Supply Voltage	VDD	V	15
Gate Supply Voltage	VGG	V	-10
Input Power	Pin	dBm	15
Flange Temperature	Tf	°C	-30 ~ +80
Storage Temperature	Tstg	°C	-65 ~ +175

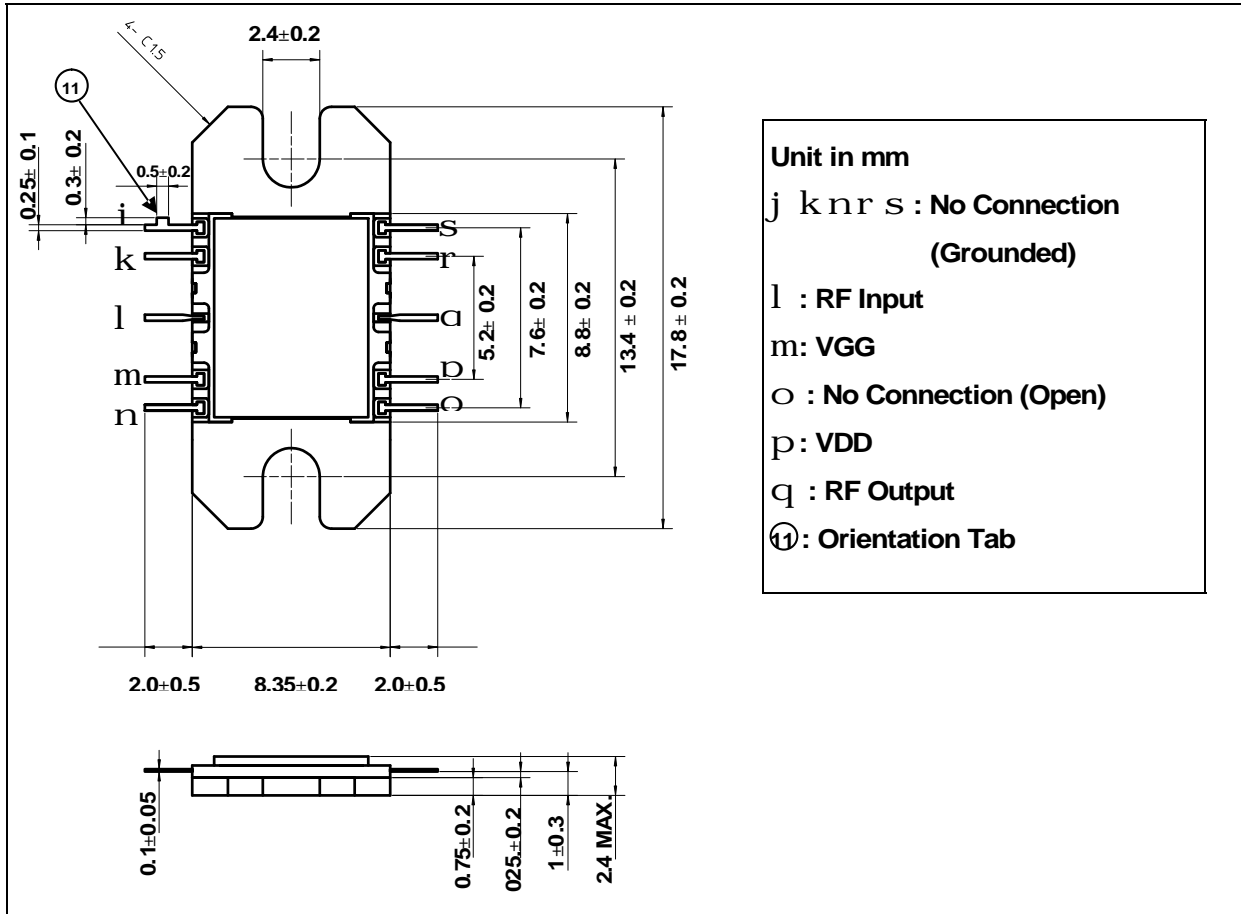
**RF PERFORMANCE SPECIFICATIONS ( Ta= 25°C )**

CHARACTERISTICS	SYMBOL	CONDITIONS	UNIT	MIN.	TYP.	MAX.
Output Power at 1dB Gain Compression Point	P1dB	VDD= 10V VGG= -5V f = 9.5 – 12.0GHz	dBm	31.0	33.0	—
Power Gain at 1dB Gain Compression Point	G1dB		dB	21.0	25.0	—
Gain Flatness	ΔG		dB	—	—	±2.5
Drain Current	IDD		A	—	1.4	1.8
Power Added Efficiency	hadd		%	—	14	—
3 <sup>rd</sup> Order Intermodulation Distortion	IM3		2 tone @ Po=19dBm(S.C.L.)	dBc	-42	-45

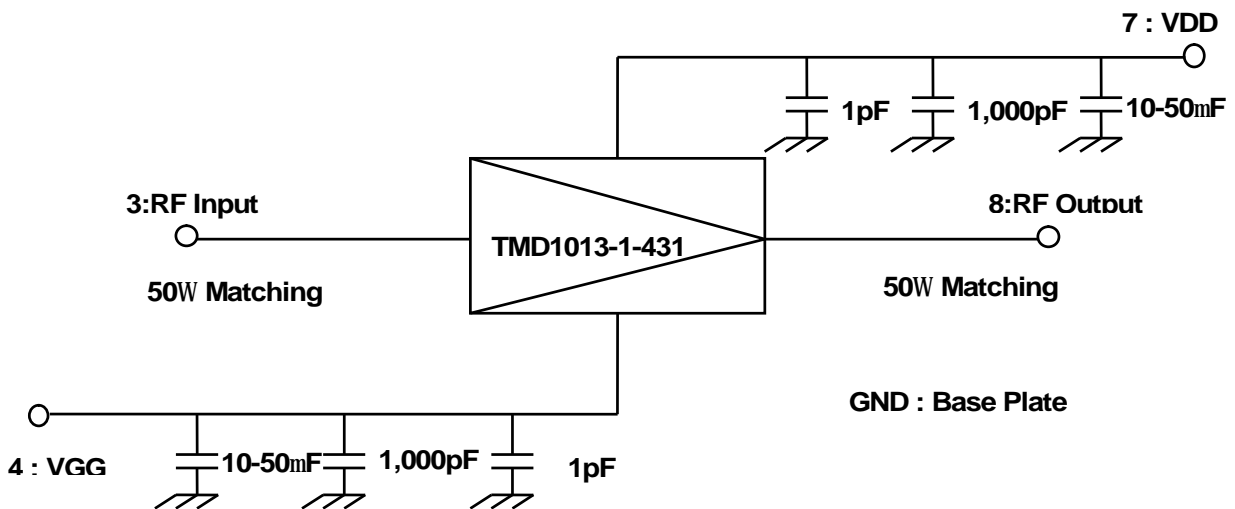
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### PACKAGE OUTLINE (2-9E1D)



### RECOMMENDED BIAS CONFIGURATION



### HANDLING PRECAUTIONS FOR PACKAGE MODEL

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C. Flanges of devices should be attached using screws and washers. Recommended torque is 0.18-0.20 N-m.